

3 Amps Surface Mount Bridge

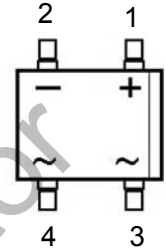
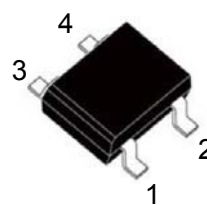


DB301S-DB307S

Features:

- ☐ Glass passivated chip junction
- ☐ Ideal for surface mounted applications
- ☐ High forward surge current capability
- ☐ High temperature soldering guaranteed:
260°C/10 seconds at terminals
- ☐ Low leakage

DB-S



Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	DB 301S	DB 302S	DB 303S	DB 304S	DB 305S	DB 306S	DB 307S	Unit
Maximum Reverse Peak Repetitive Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Output Current, 0.06" (1.5mm) lead length at Ta=40°C (Note 1)	$I_{(AV)}$	3.0							A
Peak Forward Surge Current 8.3ms single half sine wave superimposed on rated load (JEDEC Method)	I_{FSM}	80							A
Total Device Dissipation Derate above 25°C	P_D	10.4							W
Maximum Reverse Current @ rated V_R Ta = 25°C Ta = 100°C	I_R	10 1.0							μA mA
Maximum Forward Voltage @ 2.0 A	V_F	1.1							V
Typical Thermal Resistance (NOTE 1)	$R_{\theta JA}$	42							°C/W
Typical Junction Capacitance @ $V_R = 4.0$ V, $f = 1.0$ MHz	C_j	30							pF
Operating and Storage Temperature Range	T_j, T_{stg}	-55 to +150							°C

Note :1.Unit mounted on P.C.B. with 0.51"×0.51" (13×13mm) copper pads.

Typical Characteristics

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

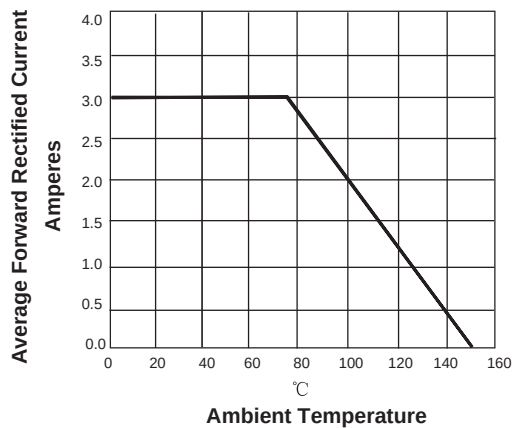


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

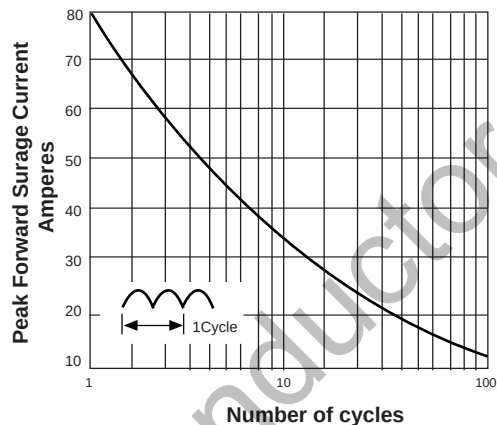


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

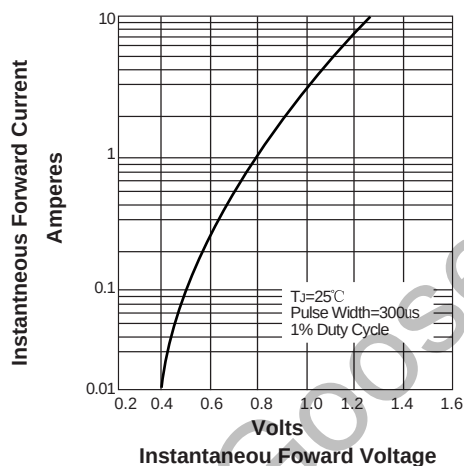


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

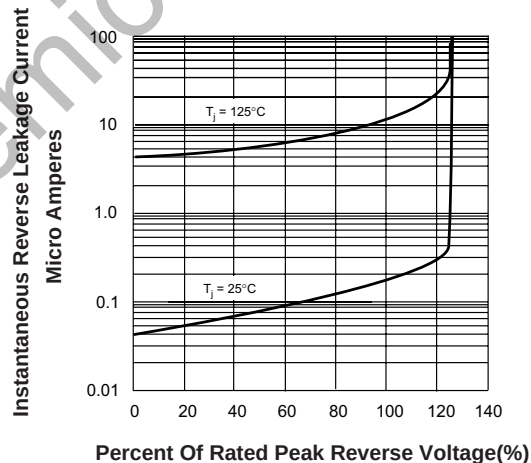
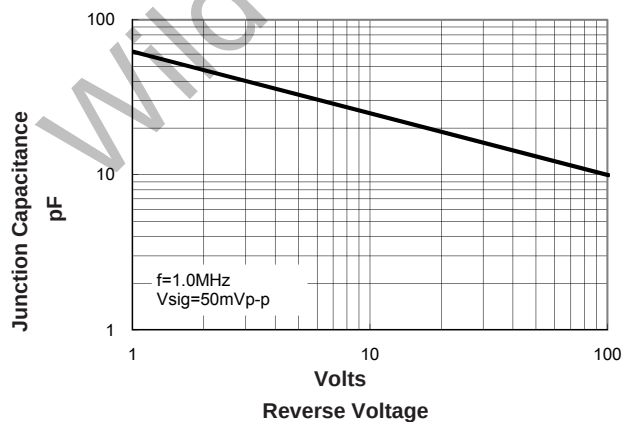


FIG. 5-TYPICAL JUNCTION CAPACITANCE



Package Dimension

DB-S

Dimensions in inches and (millimeters)